ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Pa	IPC. Bannockl	ourn, Illinois, A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declarat	ion of the su	ibstances v s all lower	vithin the manufact level materials for	turer listed which the	item. Note: i manufacture	f the item is an as has engineering	sembly with low responsibility.	
	P.1.1 IPC Web Site for Information on IPC-1752 Standard For Discrete Discre				 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Info 					Mfg Informat	ion			
Supplier Information														
Company name* Comp			Company unique ID			Unique ID Authority				Respo	Response Date*			
nsemi										2024-0	2024-05-10			
ontact Name Title - Contact			ct			Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards Product Env			nviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			esentative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Product			roduct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	M	Manufacturing Site		Weight*	UOM	Unit Type	
	NCP303	NCP303150MNTWG Integrated Driv		ver & MOSFFET		2024-05-10		T	TH6		86.36325	mg	Each	
Ianufacturing Proccess Informa	ntion													
Terminal Plating / Grid Array M	aterial	Ferminal Base A	Alloy	J-STD-020 MSL Rating		Peak Proc	ak Process Body Temperat		ure Max Time at Peak Tem		ature Numb	er of Reflow Cy	eles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	seco	onds 3			
omments														
vel 1 - maximum time at peak temperat	ure during so	ldering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.80036	mg	Supplier	Zinc (Zn)	7440-66-6		0.0082	mg
			Supplier	Iron (Fe)	7439-89-6		0.1632	mg
			Supplier	Copper (Cu)	7440-50-8		6.6236	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0054	mg
Clip Attach	0.1	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0075	mg
			Supplier	Proprietary	Proprietary Data		0.0065	mg
			Supplier	Bismaleimide	13676-54-5		0.028	mg
			Supplier	PTFE	9002-84-0		0.058	mg
Die	2.76287	mg	Supplier	Silicon (Si)	7440-21-3		2.7629	mg
Die Attach Solder	4.40103	mg	Supplier	Silver (Ag)	7440-22-4		0.11	mg
			А	Lead (Pb)	7439-92-1	7a	4.071	mg
			Supplier	Tin (Sn)	7440-31-5		0.2201	mg
Lead Frame	32.9996	mg	Supplier	Silver (Ag)	7440-22-4		1.65	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0396	mg
			Supplier	Iron (Fe)	7439-89-6		0.792	mg
			Supplier	Copper (Cu)	7440-50-8		30.4916	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0264	mg
Mold Compound-Black	36.0995	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.3465	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1805	mg
			Supplier	Silica (SiO2)	14464-46-1		31.7676	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.805	mg
lating	2.99983	mg	Supplier	Tin (Sn)	7440-31-5		2.9998	mg
Wire Bond - Cu	0.200061	mg	Supplier	Palladium (Pd)	7440-05-3		0.0036	mg
			Supplier	Gold (Au)	7440-57-5		0.0002	mg
			Supplier	Copper (Cu)	7440-50-8		0.1963	mg